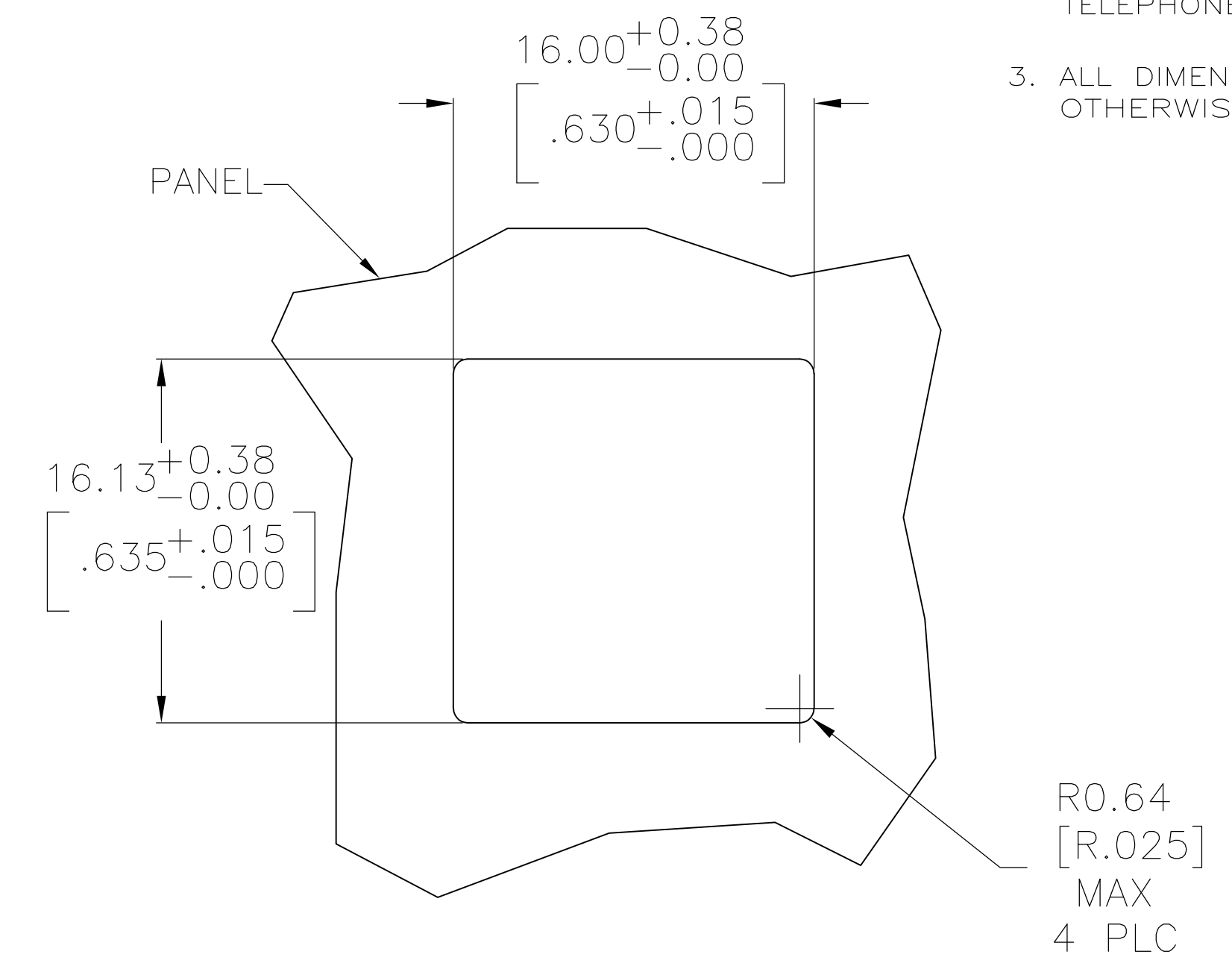
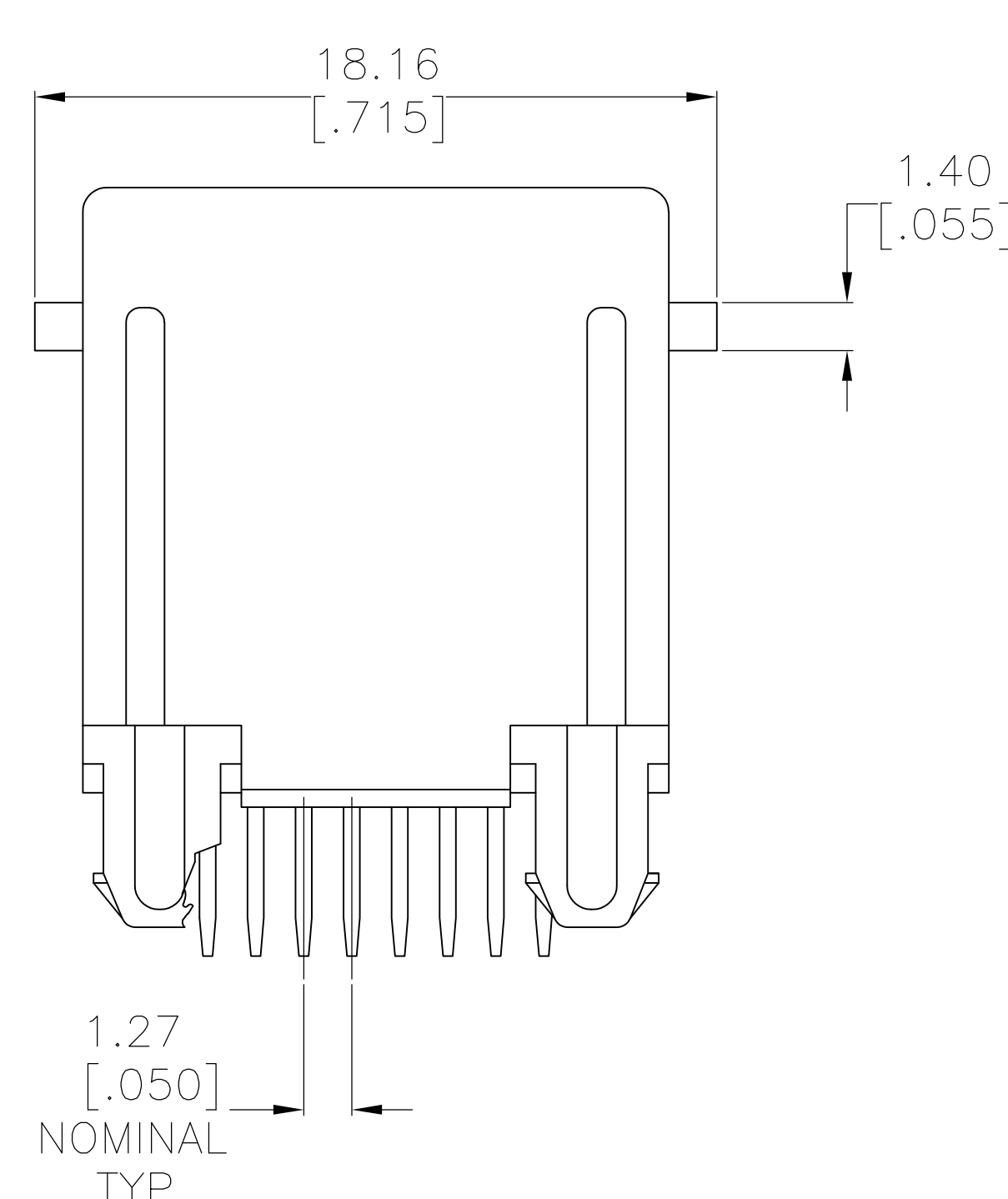
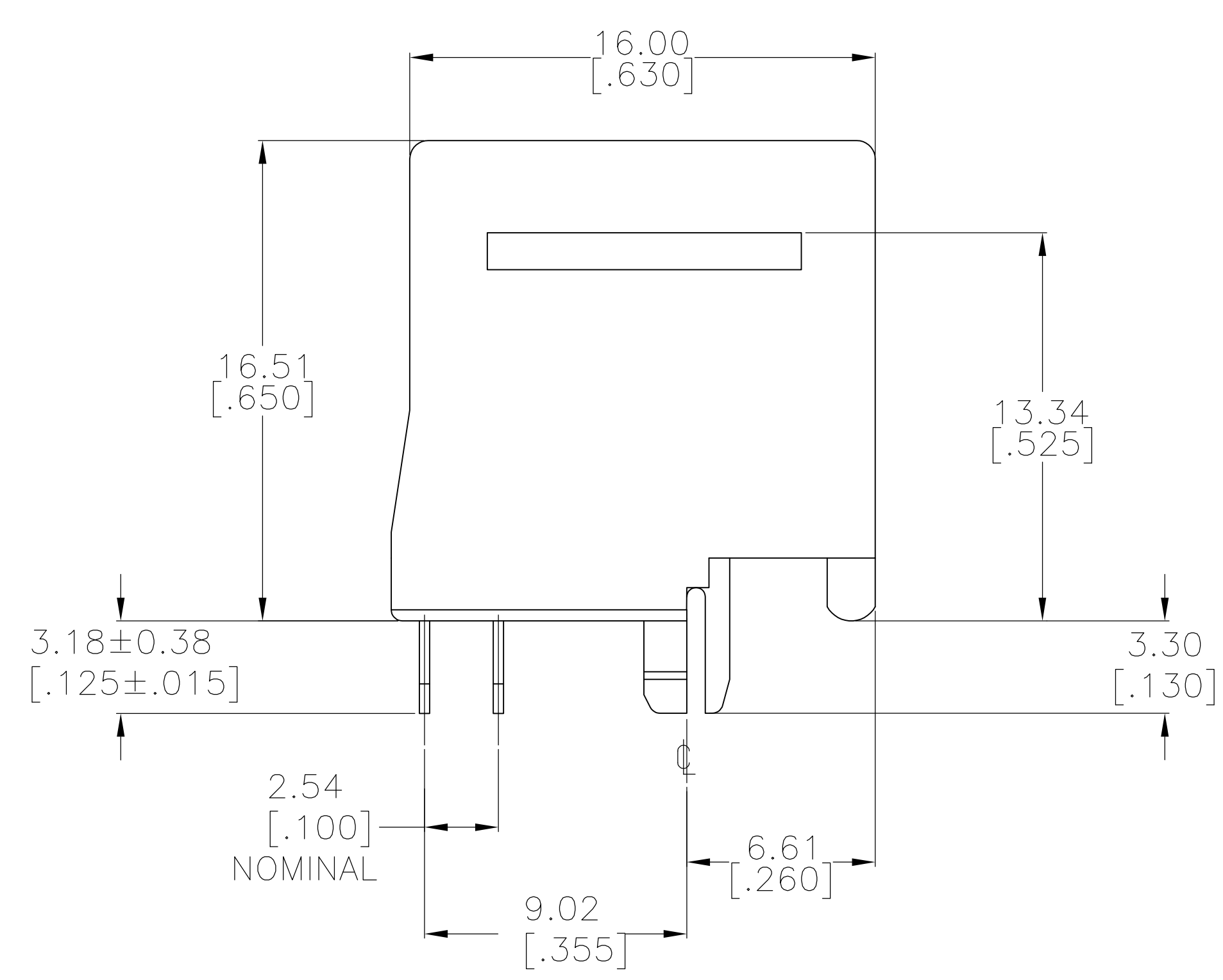
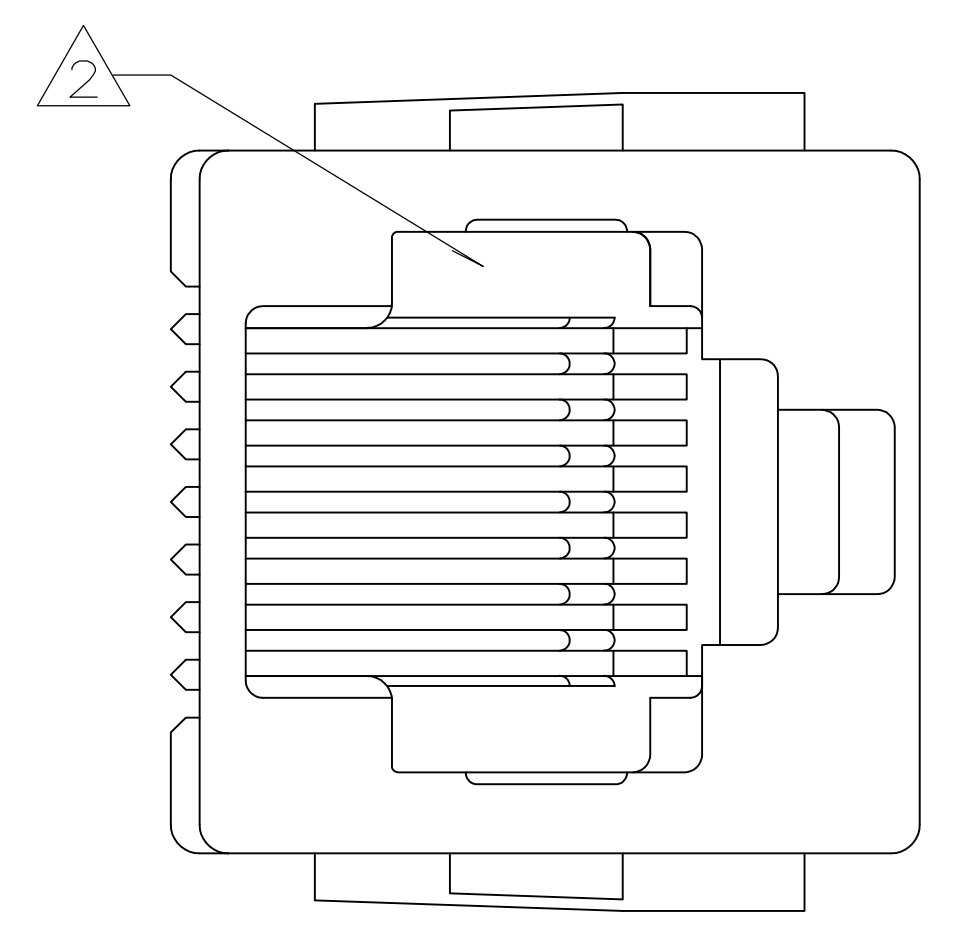
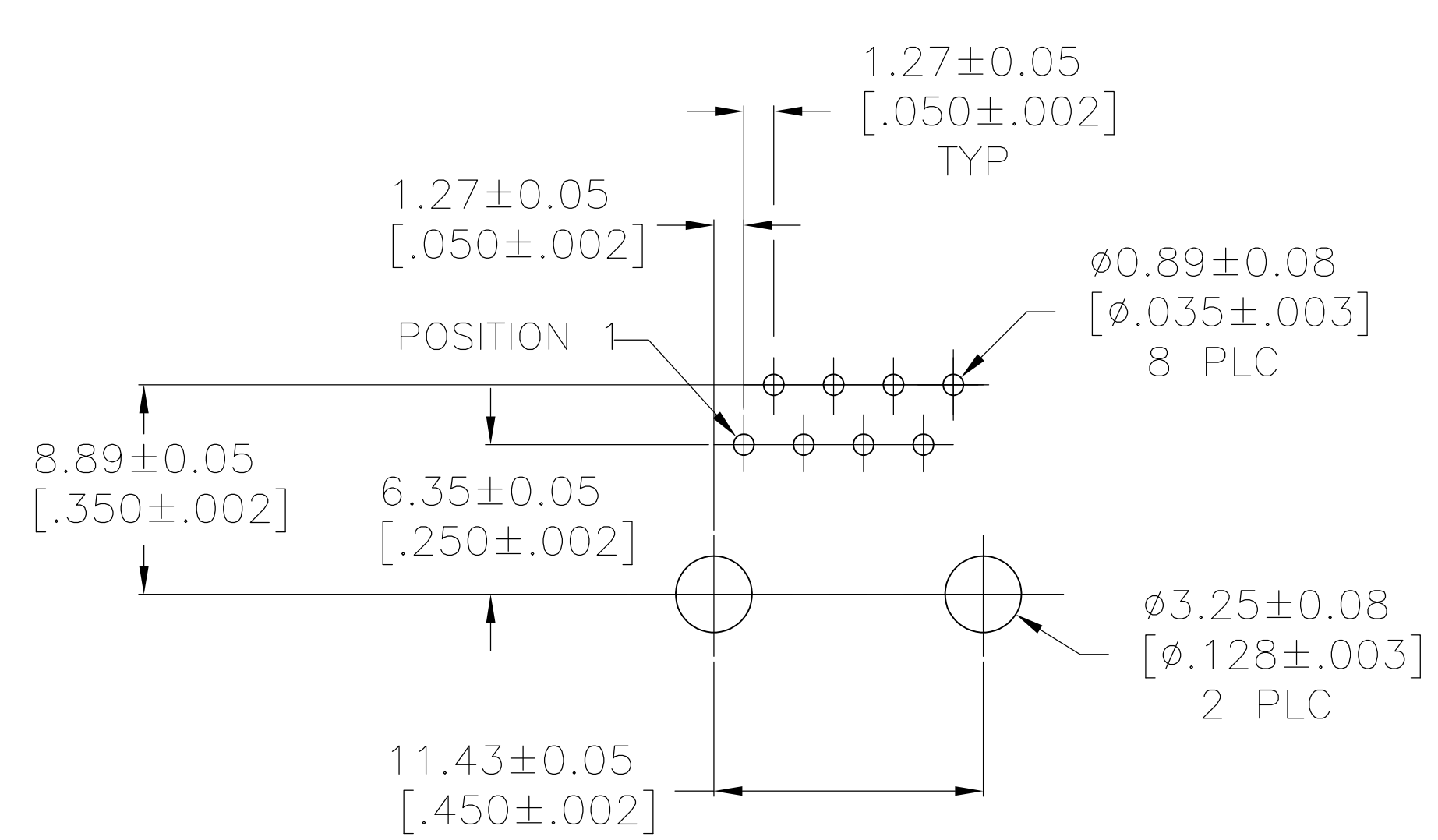


LOC		DIST		REVISIONS			
GP	00	P	LTR	DESCRIPTION	DATE	DMN	APVD
B2	REVISED PER ECO-12-014368				26SEP2012	CJV	PAR

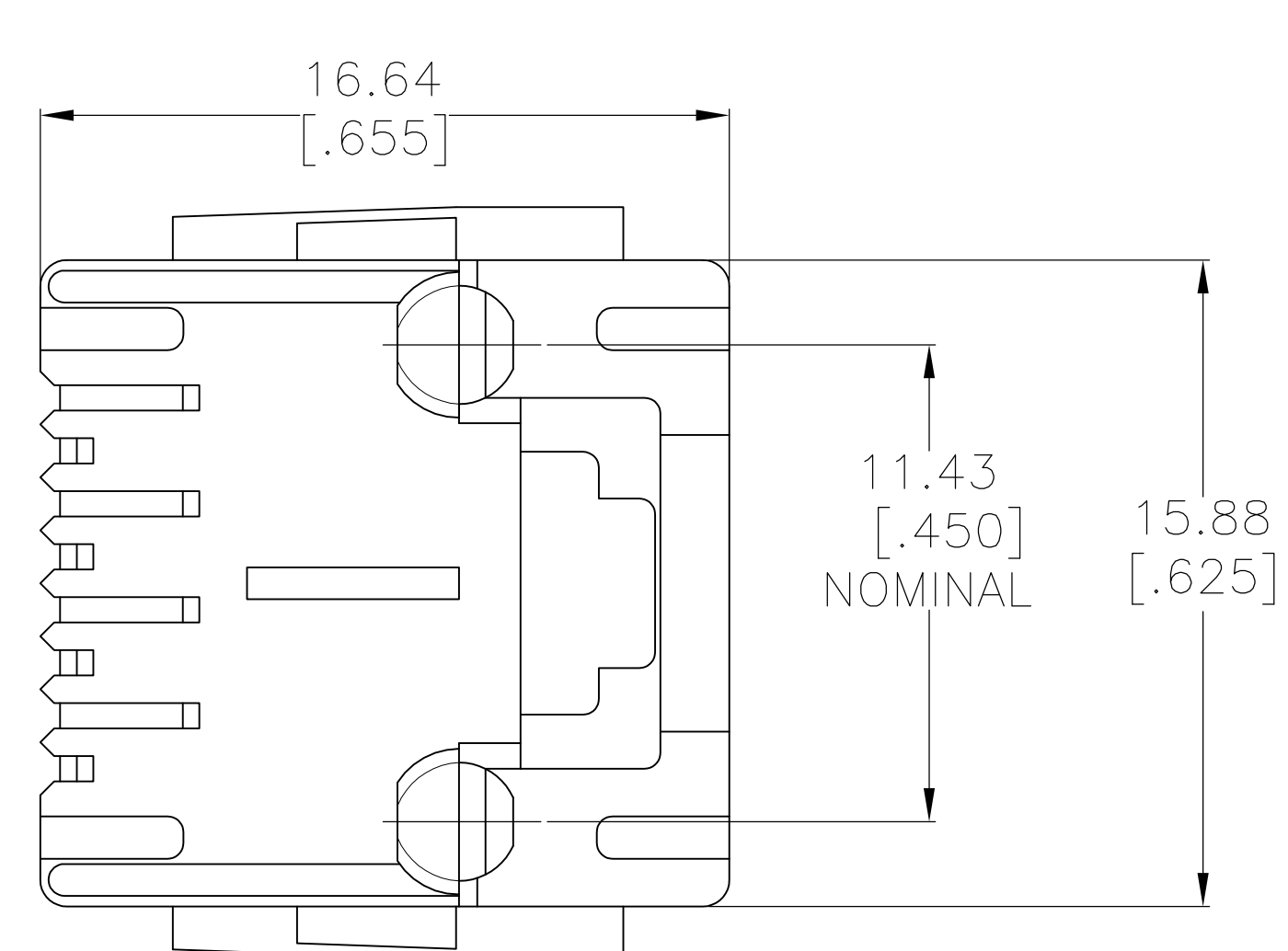
- MATERIAL: HOUSING- PBT POLYESTER, BLACK.
TERMINAL- 0.35 [.0138] THICK PHOS BRONZE PLATED WITH 1.27µm [.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 2.03µm [.000080] THICK MATTE TIN IN SOLDER AREA OVER 1.27µm [.000050] THICK NICKEL UNDERPLATE.
- CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.
- ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.



RECOMMENDED PANEL CUTOUT SCALE 4:1



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE SCALE 4:1



5520259-4
PART NO

THIS DRAWING IS A CONTROLLED DOCUMENT. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009		DWG: R.GRZYBOWSKI 05MAY05 CHK: P.RECCE 10SEP2007 APPVD: S.FLICKINGER 10SEP2007	NAME: S.FLICKINGER	DATE: 10SEP2007	RESTRICTED TO: -
DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED:	PRODUCT SPEC: 108-1163	APPLICATION SPEC: 114-2048	SIZE: A1	SCALE: 6:1
MATERIAL: SEE NOTE 1	FINISH: SEE NOTE 1	WEIGHT: -	DRAWING NO: 5520259	SHEET: 1 OF 1	REV: B2
CUSTOMER DRAWING		STE TE Connectivity			